

SCAN16512 Low Voltage Universal 16-bit IEEE 1149.1 Bus Transceiver with TRI-STATE Outputs

Check for Samples: [SCAN16512](#)

FEATURES

- IEEE 1149.1 (JTAG) Compliant
- 2.7V to 3.6V V_{CC} Operation
- TRI-STATE Outputs for Bus-Oriented Applications
- Dual Byte-Wide Data for Bus Applications
- Power Down High Impedance Inputs and Outputs
- Optional Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors (SCANH16512, SCANH162512 Versions)
- Optional 25 Ω Series Resistors in Outputs to Minimize Noise and Eliminate Termination Resistors (SCAN162512, SCANH162512 Versions)
- Supports Live Insertion/Withdrawal
- Includes CLAMP and HIGHZ Instructions

DESCRIPTION

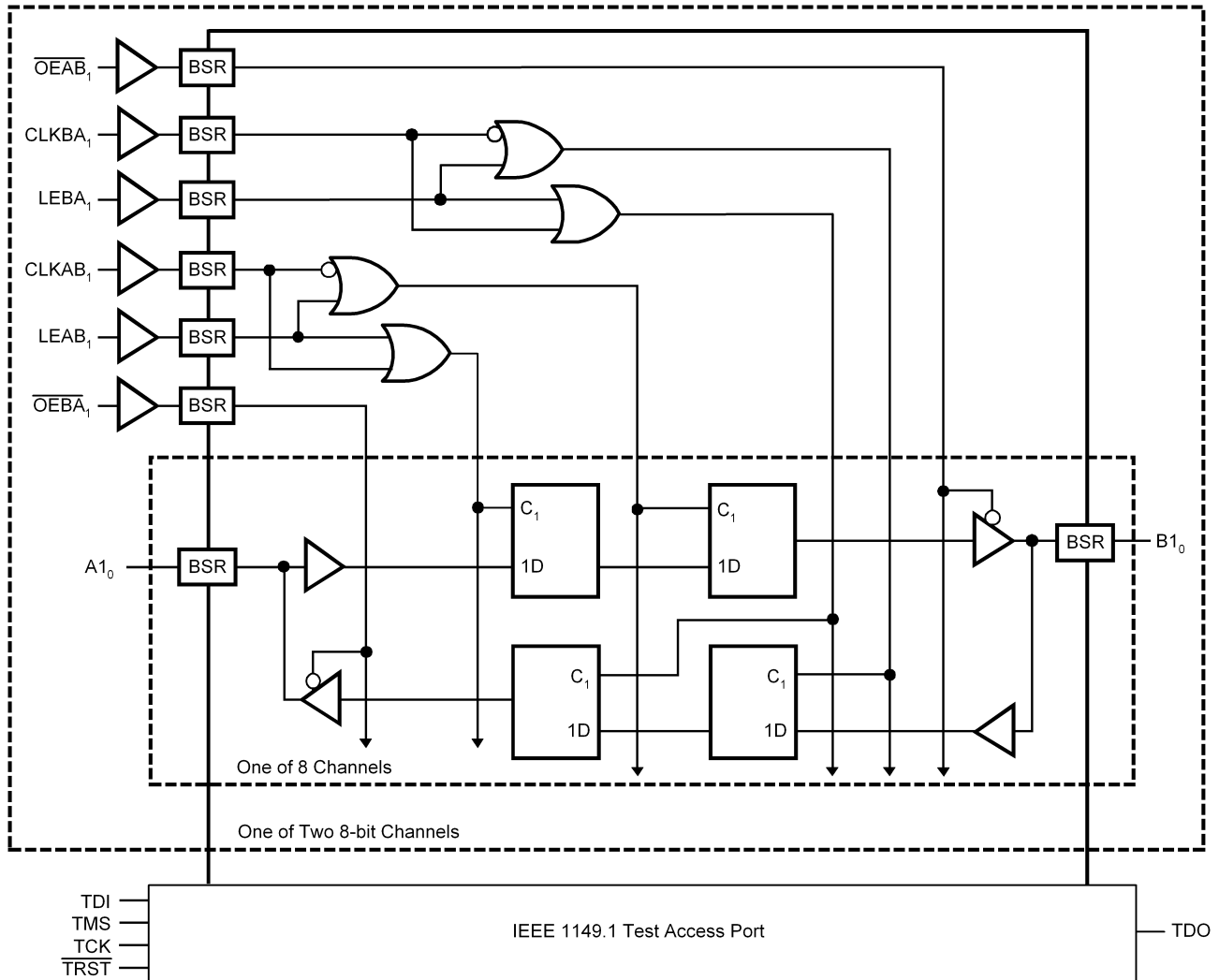
The SCAN16512 is a high speed, low-power universal bus transceiver featuring data inputs organized into two 8-bit bytes with output enable and latch enable control signals. This function is configurable as a D-type Latch or Flip-Flop, and can operate in transparent, latched, or clocked mode. This device is compliant with IEEE 1149.1 Standard Test Access Port and Boundary Scan Architecture with the incorporation of the defined boundary-scan test logic and test access port consisting of Test Data Input (TDI), Test Data Out (TDO), Test Mode Select (TMS), Test Clock (TCK), and Test Reset (TRST).



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Block Diagram



PIN DESCRIPTIONS

Pin Name	Description
A1 ₀ -A1 ₇ , A2 ₀ -A2 ₇	Normal-function A-bus I/O ports. See Function Table for normal-mode logic.
B1 ₀ -B1 ₇ , B2 ₀ -B2 ₇	Normal-function B-bus I/O ports. See Function Table for normal-mode logic.
CLKAB ₁ , CLKBA ₁ , CLKAB ₂ , CLKBA ₂	Normal-function clock inputs. See Function Table for normal-mode logic.
GND	Ground
V _{CC}	Supply Voltage
LEAB ₁ , LEBA ₁ , LEAB ₂ , LEBA ₂	Normal-function latch enables. See Function Table for normal-mode logic.
\overline{OEAB}_1 , \overline{OEBA}_1 , \overline{OEAB}_2 , \overline{OEBA}_2	Normal-function output enables. See Function Table for normal-mode logic.
TDO	The Test Data Output to support IEEE Std 1149.1-1990. TDO is the serial output for shifting data through the instruction register or selected data register.
TMS	The Test Mode Select input to support IEEE Std 1149.1-1990. TMS directs the device through it's TAP controller states. An internal pull-up forces TMS high if left unconnected.
TCK	The Test Clock input to support IEEE Std 1149.1-1990. Test operations of the device are synchronous to TCK. Data is captured on the rising edge of TCK and outputs change on the falling edge of TCK.
TDI	The Test Data Input to support IEEE Std 1149.1-1990. TDI is the serial input to shift data through the instruction register or the selected data register. An internal pull-up resistor forces TDI high if left unconnected.
\overline{TRST}	The Test Reset Input to support IEEE Std 1149.1-1990. \overline{TRST} is the asynchronous reset pin which will force the TAP controller to it's initialization state when active. An internal pullup resistor forces \overline{TRST} high if left unconnected.

BGA Pinout

	1	2	3	4	5	6	7	8
A	A1 ₀	A1 ₂	A1 ₄	A1 ₆	A2 ₀	A2 ₂	A2 ₄	A2 ₆
B	A1 ₁	A1 ₃	A1 ₅	A1 ₇	A2 ₁	A2 ₃	A2 ₅	A2 ₇
C	\overline{TRST}	CLKAB ₁	LEAB ₁	\overline{OEAB}_1	GND	CLKAB ₂	LEAB ₂	\overline{OEAB}_2
D	TMS	GND	V _{CC}	GND	V _{CC}	GND	TDI	TDO
E	TCK	GND	V _{CC}	V _{CC}	GND	GND	N/C	V _{CC}
F	CLKBA ₁	LEBA ₁	\overline{OEBA}_1	GND	N/C	CLKBA ₂	LEBA ₂	\overline{OEBA}_2
G	B1 ₁	B1 ₃	B1 ₅	B1 ₇	B2 ₁	B2 ₃	B2 ₅	B2 ₇
H	B1 ₀	B1 ₂	B1 ₄	B1 ₆	B2 ₀	B2 ₂	B2 ₄	B2 ₆

Connection Diagram

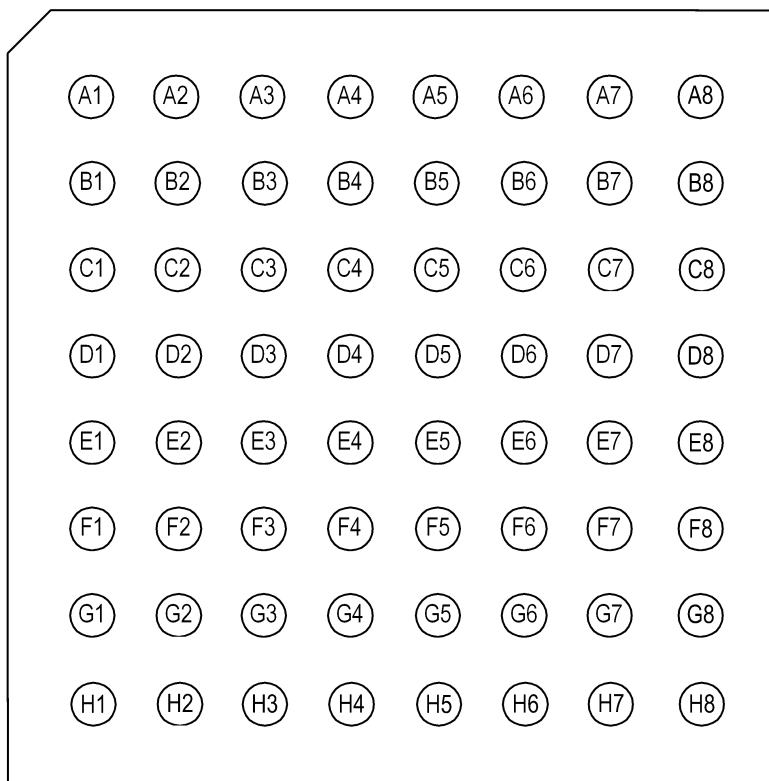


Figure 1. Top View

Function Table⁽¹⁾⁽²⁾

Inputs				Outputs
\overline{OEAB}	LEAB	CLKAB	A	B
L	L	L	X	$B_0^{(3)}$
L	L	↑	L	L
L	L	↑	H	H
L	H	X	L	L
L	H	X	H	H
H	X	X	X	Z

- (1) H = HIGH Voltage Level
 L = LOW Voltage Level
 X = Immaterial (HIGH or LOW, inputs may not float)
 Z = High Impedance
- (2) A-to-B data flow is shown. B-to-A data flow is similar, but uses \overline{OEBA} , LEBA, and CLKBA.
- (3) Output level before the indicated steady-state input conditions were established.

Functional Description

In the normal mode, these devices are 16-bit universal bus transceivers that combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, or clocked modes. They can be used as two 8-bit transceivers, or as one 16-bit transceiver. The test circuitry can be activated by the TAP to take snapshot samples of the data appearing at the device pins or to perform a self test on the boundary-test cells. Activating the TAP may affect the normal functional operation of the universal bus transceivers. When the TAP is activated, the test circuitry performs boundary-scan test operations according to the protocol described in IEEE Std 1149.1-1990.

Data flow in each direction is controlled by output-enable (\overline{OEAB} and \overline{OEBA}), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the devices operate in the transparent mode when LEAB is high. When LEAB is low, the A data is latched while CLKAB is held at a static low or high logic level. Otherwise, if LEAB is low, A data is stored on a low-to-high transition of CLKAB. When \overline{OEAB} is LOW, the B outputs are active. When \overline{OEAB} is HIGH, the B outputs are in the high-impedance state. B-to-A data flow is similar to A-to-B data flow but uses the \overline{OEBA} , LEBA, and CLKBA inputs.

Five dedicated test pins are used to observe and control the operation of the test circuitry: test data input (TDI), test data output (TDO), test mode select (TMS), test clock (TCK), and test reset (TRST). All testing and scan operations are synchronized to the TAP interface.

For details about the sequence of boundary scan cells in the SCAN16512, please refer to the BSDL (Boundary Scan Description Language) file available on our website.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾

Supply Voltage (V_{CC})		-0.5V to +4.6V
DC Input Diode Current (I_{IK})	$V_I = -0.5V$	-50 mA
DC Output Diode Current (I_{OK})	$V_O = -0.5V$	-50 mA
DC Input Voltage (V_I)		-0.5V to 4.6V
DC Output Voltage (V_O)		-0.5V to 4.6V
DC Output Source/Sink Current (I_O)		± 50 mA
DC V_{CC} or Ground Current per Supply Pin		± 100 mA
Junction Temperature		+150°C
Storage Temperature		-65°C to +150°C
Lead Temperature (Solder, 4sec)	64L BGA	220 °C
Thermal Resistance	BGA θ_{JA}	62°C/W
Package Derating		16.1mW/°C above 25°C
ESD (Min)		1000V

(1) Absolute maximum ratings are those values beyond which damage to the device may occur.

Recommended Operating Conditions

Supply Voltage (V_{CC})	SCAN16512	2.7V to 3.6V
Input Voltage (V_I)		0V to 3.6V
Output Voltage (V_O)		0V to 3.6V
Operating Temperature (T_A)	Industrial	-40°C to +85°C

DC Electrical Characteristics

Symbol	Parameter	V _{CC} (V)	Industrial		Military		Units	Conditions
			T _A = -40°C to +85°C		T _A = -55°C to +125°C			
			Min	Max	Min	Max		
V _{IH}	Minimum High Input Voltage	2.7	2.0		2.0		V	V _{OUT} = 0.1V or V _{CC} - 0.1V
		3.6	2.0		2.0			
V _{IL}	Maximum Low Input Voltage	2.7		0.8		0.8	V	V _{OUT} = 0.1V or V _{CC} - 0.1V
		3.6		0.8		0.8		
V _{OH}	Minimum High Output Voltage All Outputs, All Options	2.7	2.5		2.5		V	I _{OUT} = -100 µA
		3.6	3.4		3.4			
	Minimum High Output Voltage TDO Outputs, All Options	2.7	2.2		2.2		V	V _{IN} = V _{IL} or V _{IH} , I _{OH} = -12mA
		3.0	2.2		2.2			
	Minimum High Output Voltage A and B Ports: SCAN16512 and SCANH16512 options	2.7	2.2		2.2		V	V _{IN} = V _{IL} or V _{IH} , I _{OH} = -12mA
		3.0	2.2		2.2			
	Minimum High Output Voltage A and B Ports: SCAN162512 and SCANH162512 options (25Ω series resistor options)	2.7	2.2		2.2		V	V _{IN} = V _{IL} or V _{IH} , I _{OH} = -4mA
		3.0	2.2		2.2			
V _{OL}	Maximum Low Output Voltage All Outputs, All Options	2.7		0.2		0.2	V	I _{OUT} = 100 µA
		3.6		0.2		0.2		
	Maximum Low Output Voltage TDO Outputs, All Options	2.7		0.4		0.4	V	V _{IN} = V _{IL} or V _{IH} , I _{OL} = 12mA
		3.0		0.55		0.55		
	Maximum Low Output Voltage A and B Ports: SCAN16512 and SCANH16512 Options	2.7		0.4		0.4	V	V _{IN} = V _{IL} or V _{IH} , I _{OL} = 12mA
		3.0		0.55		0.55		
	Maximum Low Output Voltage A and B Ports: SCAN162512 and SCANH162512 Options (25Ω series resistor options)	2.7		0.4		0.4	V	V _{IN} = V _{IL} or V _{IH} , I _{OL} = 4mA
		3.0		0.6		0.6		
I _{IN}	Maximum Input Leakage Current	3.6		±5.0		±5.0	µA	V _I = V _{CC} , GND
I _{ILR}	Input Low Current	3.6		-200		-200	µA	V _{IN} = GND
I _{OZ}	Maximum I/O Leakage Current	3.6		±5.0		±5.0	µA	V _I (OE) = V _{IL} , V _{IH} V _I = V _{CC} , GND V _O = V _{CC} , GND

DC Electrical Characteristics (continued)

Symbol	Parameter	V _{CC} (V)	Industrial		Military		Units	Conditions
			T _A = -40°C to +85°C		T _A = -55°C to +125°C			
			Min	Max	Min	Max		
I _{I(HOLD)}	Bus Hold Input Minimum Drive Hold Current ⁽¹⁾	2.7	±75		±75		µA	V _I = 0.8V or 2.0V
		3.6		±625		±625		V _I = 0 to 3.6V
V _{IKL}	Input Clamp Diode Voltage	2.7		-1.5		-1.5	V	I _{IN} = -18mA
I _{OFF}	Power-off Leakage Current	0.0		±10.0		±10.0	µA	V _O = V _{CC} , GND
I _{CC}	Maximum Quiescent Supply Current	3.6		20		20	µA	
I _{CCt}	Maximum I _{CC} Per Input	3.6		0.5		0.5	mA	V _I = V _{CC} -0.6V

(1) Applies to devices with Bus Hold feature only.

Noise Specifications

Applies to SCAN16512 and SCANH16512 options, C_L = 30pF, R_L = 500Ω to GND

Symbol	Parameter	V _{CC} (V)	Industrial, Military		Units
			T _A = 25°C		
			Typical Limits		
V _{OLP}	Quiet Output Maximum Dynamic VOL ⁽¹⁾	3.3	1.2		V
V _{OLV}	Quiet Output Minimum Dynamic VOL ⁽¹⁾	3.3	-1.5		V
V _{OHP}	Quiet Output Maximum Dynamic VOH ⁽²⁾	3.3	VOH + 0.9		V
V _{OHV}	Quiet Output Minimum Dynamic VOH ⁽²⁾	3.3	VOH - 1.5		V

- (1) Maximum number of outputs is defined as n. (n-1) outputs are switched LOW while the quiet output is monitored in a LOW (VOL) state. Also, (n-1) outputs are switched HIGH while the quiet output is monitored in a LOW (VOL) state.
- (2) Maximum number of outputs is defined as n. (n-1) outputs are switched LOW while the quiet output is monitored in a HIGH (VOH) state. Also, (n-1) outputs are switched HIGH while the quiet output is monitored in a HIGH (VOH) state.

Noise Specifications

Applies to SCAN162512 and SCANH162512 options, C_L = 30pF, R_L = 500Ω to GND

Symbol	Parameter	V _{CC} (V)	Industrial, Military		Units
			T _A = 25°C		
			Typical Limits		
V _{OLP}	Quiet Output Maximum Dynamic VOL ⁽¹⁾	3.3	0.6		V
V _{OLV}	Quiet Output Minimum Dynamic VOL ⁽¹⁾	3.3	-0.5		V
V _{OHP}	Quiet Output Maximum Dynamic VOH ⁽²⁾	3.3	VOH + 0.5		V
V _{OHV}	Quiet Output Minimum Dynamic VOH ⁽²⁾	3.3	VOH - 0.6		V

- (1) Maximum number of outputs is defined as n. (n-1) outputs are switched LOW while the quiet output is monitored in a LOW (VOL) state. Also, (n-1) outputs are switched HIGH while the quiet output is monitored in a LOW (VOL) state.
- (2) Maximum number of outputs is defined as n. (n-1) outputs are switched LOW while the quiet output is monitored in a HIGH (VOH) state. Also, (n-1) outputs are switched HIGH while the quiet output is monitored in a HIGH (VOH) state.

AC Electrical Characteristics

Normal Operation, over recommended operating supply voltage and temperature ranges unless otherwise specified.

Symbol	Parameter	SCAN16512, SCANH16512		SCAN16512, SCANH16512		Units
		$T_A = -40^{\circ}\text{C to }+85^{\circ}\text{C}$		$T_A = -55^{\circ}\text{C to }+125^{\circ}\text{C}$		
		$C_L = 30\text{ pF}$ $R_L = 500\Omega\text{ to GND}$		$C_L = 30\text{ pF}$ $R_L = 500\Omega\text{ to GND}$		
		Min	Max	Min	Max	
t_{PLH} , t_{PHL}	Propagation Delay A to B, B to A		5.5		6.5	ns
t_{PLH} , t_{PHL}	Propagation Delay CLKAB to B, CLKBA to A		6.0		7.0	ns
t_{PLH} , t_{PHL}	Propagation Delay LEAB to B, LEBA to A		6.0		7.0	ns
t_{PLZ} , t_{PHZ}	Disable Time, \overline{OEAB} to B, \overline{OEBA} to A		7.5		8.0	ns
t_{PZL} , t_{PZH}	Enable Time, \overline{OEAB} to B, \overline{OEBA} to A		7.5		8.0	ns

AC Electrical Characteristics

Normal Operation, over recommended operating supply voltage and temperature ranges unless otherwise specified.

Symbol	Parameter	SCAN162512		SCAN162512		Units
		$T_A = -40^{\circ}\text{C to }+85^{\circ}\text{C}$		$T_A = -55^{\circ}\text{C to }+125^{\circ}\text{C}$		
		$C_L = 30\text{ pF}$ $R_L = 500\Omega\text{ to GND}$		$C_L = 30\text{ pF}$ $R_L = 500\Omega\text{ to GND}$		
		Min	Max	Min	Max	
t_{PLH} , t_{PHL}	Propagation Delay A to B, B to A		6.0		7.0	ns
t_{PLH} , t_{PHL}	Propagation Delay CLKAB to B, CLKBA to A		6.5		7.5	ns
t_{PLH} , t_{PHL}	Propagation Delay LEAB to B, LEBA to A		6.5		7.5	ns
t_{PLZ} , t_{PHZ}	Disable Time, \overline{OEAB} to B, \overline{OEBA} to A		7.5		8.0	ns
t_{PZL} , t_{PZH}	Enable Time, \overline{OEAB} to B, \overline{OEBA} to A		7.5		8.0	ns

AC Electrical Characteristics

Normal Operation, over recommended operating supply voltage and temperature ranges unless otherwise specified.

Symbol	Parameter	SCANH162512		SCANH162512		Units
		$T_A = -40^\circ\text{C to }+85^\circ\text{C}$		$T_A = -55^\circ\text{C to }+125^\circ\text{C}$		
		$C_L = 30\text{ pF}$ $R_L = 500\Omega\text{ to GND}$		$C_L = 30\text{ pF}$ $R_L = 500\Omega\text{ to GND}$		
		Min	Max	Min	Max	
t_{PLH}	Propagation Delay		6.0		7.0	ns
t_{PHL}	A to B, B to A		6.0		7.0	
t_{PLH}	Propagation Delay		6.5		7.5	ns
t_{PHL}	CLKAB to B, CLKBA to A		6.5		7.5	
t_{PLH}	Propagation Delay		6.5		7.5	ns
t_{PHL}	LEAB to B, LEBA to A		6.5		7.5	
t_{PLZ}	Disable Time, \overline{OEAB} to B, \overline{OEBA} to A		7.5		8.0	ns
t_{PHZ}			7.5		8.0	
t_{PZL}	Enable Time, \overline{OEAB} to B, \overline{OEBA} to A		8.0		8.0	ns
t_{PZH}			8.0		8.0	

AC Operating Requirements

Normal Operation, over recommended operating supply voltage and temperature ranges unless otherwise specified

Symbol	Parameter	All Options		All Options		Units
		$T_A = -40^\circ\text{C to }+85^\circ\text{C}$		$T_A = -55^\circ\text{C to }+125^\circ\text{C}$		
		$C_L = 30\text{ pF}$ $R_L = 500\Omega\text{ to GND}$		$C_L = 30\text{ pF}$ $R_L = 500\Omega\text{ to GND}$		
		Ensured Minimum	Ensured Minimum			
t_S	Setup Time, A to CLKAB or B to CLKBA		1.5		1.5	ns
t_H	Hold Time, A to CLKAB or B to CLKBA		2.0		2.0	ns
t_S	Setup Time, A to LEAB or B to LEBA		1.5		1.5	ns
t_H	Hold Time, A to LEAB or B to LEBA		2.5		2.5	ns
t_W	Pulse Width, CLKAB or CLKBA, high or low		2.0		2.0	ns
t_W	Pulse Width, LEAB or LEBA high		2.0		2.0	ns
f_{max}	Maximum CLKAB or CLKBA Clock Frequency		250		250	MHz

AC Operating Requirements

can Test Operation, over recommended operating supply voltage and temperature ranges unless otherwise specified

Symbol	Parameter	All Options		All Options		Units
		$T_A = -40^\circ\text{C to }+85^\circ\text{C}$		$T_A = -55^\circ\text{C to }+125^\circ\text{C}$		
		$C_L = 30\text{ pF}$ $R_L = 500\Omega\text{ to GND}$		$C_L = 30\text{ pF}$ $R_L = 500\Omega\text{ to GND}$		
		Ensured Minimum	Ensured Minimum			
t_S	Setup Time, H or L, TMS to TCK		2.0		2.0	ns
t_H	Hold Time, H or L, TCK to TMS		1.0		1.0	ns
t_S	Setup Time, H or L, TDI to TCK		1.0		1.0	ns
t_H	Hold Time, H or L, TCK to TDI		2.0		2.0	ns
t_W	Pulse Width TCK High or Low		10		10	ns
t_W	Pulse Width \overline{TRST} , Low		2.5		2.5	ns
f_{max}	Maximum TCK Clock Frequency		25		25	MHz
t_{REC}	Recovery Time, \overline{TRST} to TCK		2.0		2.0	ns

AC LOADING AND WAVEFORMS

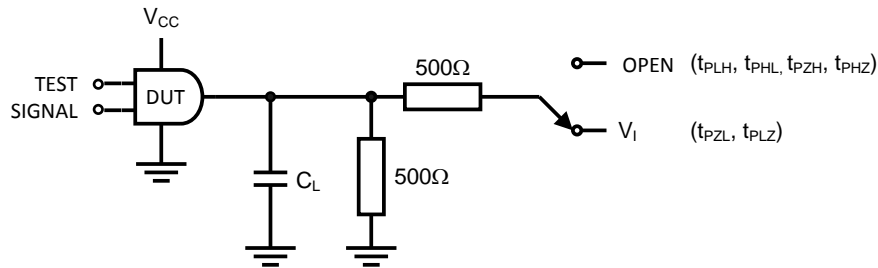
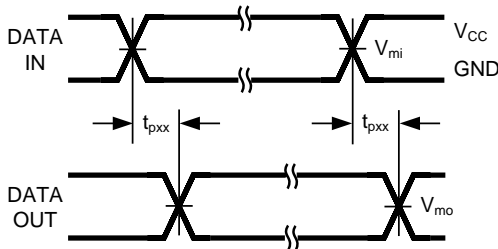
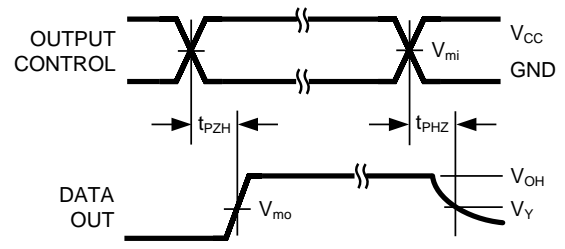


Figure 2. AC Test Circuit (C_L Includes Probe and Jig Capacitance)

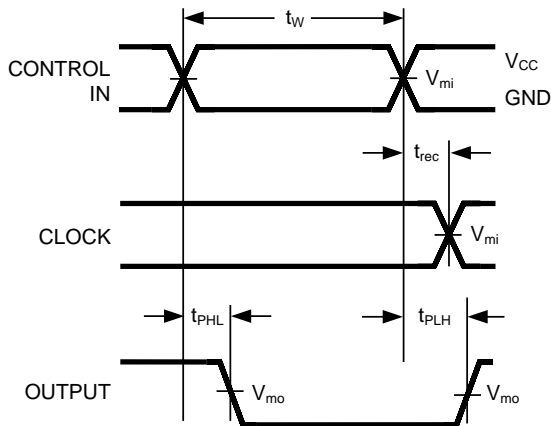
V_I	C_L
$V_{CC} * 2$	30pF



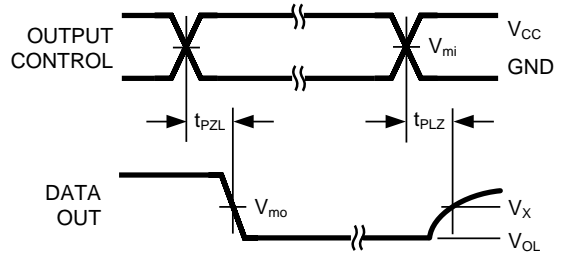
Waveform for Inverting and Non-inverting Functions



Tristate Output High Enable and Disable Times for Logic



Propagation Delay, Pulse Width and t_{REC} Waveforms



Tristate Output Low Enable and Disable Times for Logic

Figure 3. Timing Waveforms (Input Characteristics; $f = 1\text{MHz}$, $t_r = t_f = 2.5\text{ns}$)

Symbol	V_{CC}
	2.7 - 3.6V
V_{mi}	1.5V
V_{mo}	1.5V
V_x	$V_{OL} + 0.3V$
V_y	$V_{OH} - 0.3V$

Capacitance and I/O Characteristics

Refer to TI's website for IBIS models at www.ti.com/lscds/ti/analog/interface.page

Table 1. Device ID Register

Ordering Code	Features	Device ID	Manufacturer & LSB
SCAN16512SM	No bus hold, no series resistor	FC30	01F
SCANH16512SM	With bus hold only	FC31	01F
SCAN162512SM	With 25Ω series resistors in outputs	FC32	01F
SCANH162512SM	With 25Ω series resistors and bus hold	FC33	01F

REVISION HISTORY

Changes from Revision C (April 2013) to Revision D	Page
• Changed layout of National Data Sheet to TI format	11

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No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

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